1. Configuration:	Rite Track 90-S Coat/Develop Track System (set-up for 200mm Si and Glass wafers)

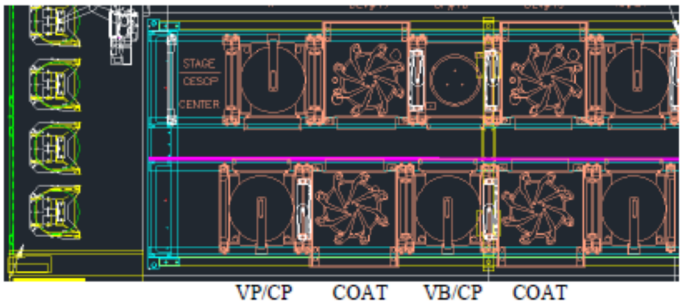
2. **Price:** **Existing configuration includes items listed below**

Model	QTY	Description
CABINET	1	Stainless Steel Paneled Cabinet – 1530mm D x 3734mm L x ~**2290mm H***
SHUTTLE	1	90-S Shuttle Arm
9002TA	4	90 Serial Transfer Arm
9068CES	1	Cassette End Station with integrated Control module: 4 cassettes – 1 x 100mm, 3 x 200mm
	1	Stacked 3-pin transfer stage and CP/Centering stage
	1	USB drive in place of floppy drive in controller
	1	Flash drive in place of hard drive in controller
9026COAT	3	Coater Module: with three (3) nozzles
	9	TalonTech TP-12 pumps, up to 800 cP - (3 per Coater)
	9	0.1um resist filters
	3	Pump-out drain to customer drain connection; rear exhaust connections
9032DEV	1	Developer Module:
	1	Dual-stream Dual Develop/DI Water dispense nozzle assembly
	1	Direct rear drain connection; rear exhaust connections
9038VP-S	1	HMDS Vapor Prime Modules (fixed pins: - proximity)
	1	Air venturi for chamber vacuum
9036VB-S	5	Vacuum Bake Module (fixed pins: - proximity)
	3	Air venturi for chamber vacuum
9036VB	1	Vacuum Bake Module (programmable pin lift)
	1	Air Venturi for chamber vacuum
9044CP-S	2	Chill Plate Module (fixed pins: - proximity)
9044CP	1	Chill Plate Module (fixed pins: - proximity)
ENVR ENCL	1	Upper enclosure with FFU units
9064FTC	1	Fluid Temperature Control, 4-bath – remoted
CHEM CAB	1	Chemical Cabinet with: (remoted)
	3	* 5-gallon solvent canister, manual-fill type, with low level and N2 pressure alarms
	2	* 5-gallon develop canister, manual-fill type, with low level and N2 pressure alarms
	1	* 1-gallon HMDS canister, manual-fill type, with low level sensor and N2 pressure alarm
SAFETY SPECS	9	* 4L resist bottle storage with L/E Assy. and low alarms (RT supplied bottle caps)
	1	CE Marking

Option:

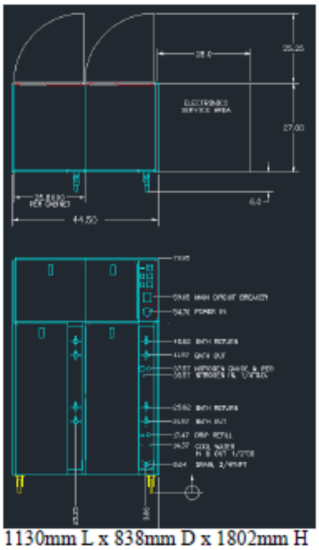
SECS HW/SW Option

VB/VB DEV CP COAT VB/VB

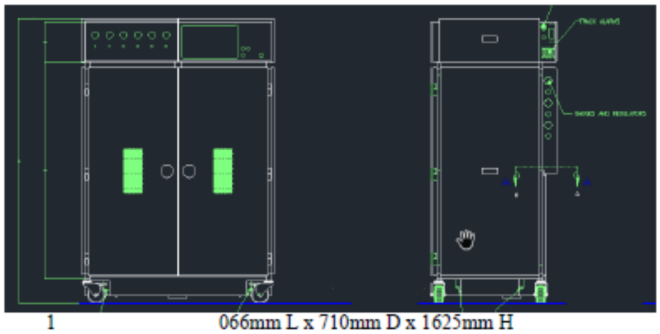


VP/CP COAT VB/CP COAT

90 Series VB



1130mm L x 838mm D x 1802mm H



1 066mm L x 710mm D x 1625mm H

3. **Module descriptions:**

a) **COATER - 9026COAT**

- High performance/High acceleration spin motor
- Iris wafer centering mechanism
- Backside EBR dispense
- Independent Topside EBR dispense arm
- Dispense nozzles solvent vapor bath
- Teflon/S.S. catch cup with splash shields
- Drain/exhaust separation
- Spin motor/vacuum chuck temperature isolation and cooling

- Programmable radial dispense arm with removable nozzle block
- Safety process cover with interlock
- Event programmable exhaust flow controller
- Teflon-lined, braided stainless steel plumbing for solvent lines
- Pressurized solvent delivery system
- In-line flow meters for Topside EBR, Backside EBR(s) and Solvent Vapor Bath
- Low contact Kel-F vacuum chuck

b) VACUUM BAKE – 9036VB-S

- Stacked modules
- Pull-out, easy access design
- 80 - 250°C temp. operation
- Teflon impregnated hard anodized chuck surface
- Air cylinder driven wafer pin lift assy.
- Fixed proximity only wafer baking
- Continuous Hot Plate exhaust with lid assy.
- Safety process cover interlock
- Safety over-temp protection device
- Point of use 0.05 micron gas filtration
- Individual pressure and flow controls for Nitrogen process/purge dispenses
- Dehydration or vacuum bake capability
- Vacuum chamber pressure interlock/display
- Air Venturi vacuum used for chamber vacuum
- Integrated heater element/chuck

c) VAPOR PRIME - 9038VP-S

- Stacked module
- Pull-out, easy access design
- 80 - 200oC temp. operation
- PID temperature controlled hotplate
- Fixed proximity only wafer baking
- Teflon impregnated hard anodized chuck surface
- Air cylinder driven wafer pin lift assy.
- N2 bubbler type dispensing system
- Uniform HMDS/N2 dispenses
- Programmable process sequences
- SEMI S2-93 compliant secondary exhaust enclosure
- Safety over-temp protection
- Safety process cover interlock
- Isolated plumbing/electronics
- Teflon lined/braided stainless steel dispense/exhaust plumbing
- Point of use 0.05 micron gas filtration
- Individual pressure and flow control
- Vacuum chamber pressure interlock/display
- Integrated heater element/chuck

d) DEVELOPER 9032/ 9032-S DEV

- High performance/Standard acceleration spin motor
- Programmable, moveable dispense arm for developer and DI water dispense nozzles
- Dual stream high flow, low impact dispense for developer solutions, (pressurized)
- Spray and stream DI water rinse nozzles
- Backside DI water rinse
- Iris wafer centering mechanism
- Event programmable exhaust flow controller
- Temperature controlled developer and DI water dispenses
- Non-metallic developer and DI water fluid paths- except S.S. spray nozzles
- Teflon/PVDF developer and DI water flow meters and plumbing
- Safety process cover with interlock
- Off-wafer dispense nozzles, stand-by area in cup
- Polyethylene catch cup
- Programmable dispense nozzles/wafer height
- Polypropylene Direct Drain
- Spin motor oscillation capability
- Independent module and chuck leveling capability
- D.I. Water idle dispense capability

- Low contact Kel-F vacuum chuck

e) SERIAL TRANSFER ARM 9002-TA
- Servo motor controlled wafer transfer arm with encoder
- Teflon coated ceramic wafer contacting surface
- Protective transfer arm covers
- Easy keyboard calibration
- Arm safety overdrive protection
- Z motion capability

f) Cassette End Station (CES) 9068 CES
- Four cassette capability
- Ergonomic 900 mm cassette height
- Cassette mapping and cross-slotted wafer detection
- Send, Receive or SendCeiver capability to stationary cassettes
- Stacked 3-pin input stage and CP/Centering output stage
- Independent shuttle/arm wafer transfer system
- Spin motor controller packaging
- System power distribution/circuit breaker box
- Main system EMO
- Electropolished S.S. panels
- LCD flat panel display
- Operator membrane keypad and pull-down keyboard
- Industrial Pentium PC AT
- 3 color status indicating tower light
- Audible alarm

g) "Z" - SHUTTLE/ARM
- Stacked module wafer transfer
- High speed, high acceleration transfer capability
- Servo motor controlled drive assembly with encoder
- Automatic shuttle home position calibration
- Servo motor controlled wafer transfer arm with encoder
- Teflon coated ceramic wafer contacting surface
- Protective transfer arm covers
- Easy keyboard shuttle and arm calibration
- Shuttle and arm safety overdrive protection

h) 9064 FLUID TEMPERATURE CONTROLLER (FTC)
- Four independent temperature controlled water baths
- Supports high flow and remote location applications
- Programming/display at system supervisor via RS422 comm.
- CFC free, thermoelectric cooling
- Local display of status and temperatures
- Stainless Steel panels on a modular steel frame
- Enclosed, exhausted cabinet
- GFI circuit breakers

i) CHILL PLATE - 9044CP-S
- Stacked module
- Pull-out, easy access design
- Water cooled Chill Plate
- Temperature monitoring
- Teflon impregnated hard anodized chuck surface
- Air cylinder driven wafer pin lift assy.
- Fixed proximity only wafer cooling

j) MAIN SYSTEM CABINET
- Rigid steel frame with electropolished stainless steel doors
- Mirror finish S.S. process covers and deck shields
- Rigid casting braces for module placement and support
- Large casters and topside footpad leveling capability
- Separate wire and pneumatic race-ways for cable/tubing harnesses

- Easily removable doors/panels
- Aerodynamic flow-thru system cabinet design
- Drip trays under all pumps, solenoid valves and filters for spill containment
- Slide out drawer for coater and/or developer gauges and flow meters
- Independent system exhaust for coater and developer modules
- Air purge of all brush motors
- Facilities interlock sensors/gauges
- Multiple system cabinet EMOs